

Single N-Channel MOSFET

Features

- ★ Advanced Trench MOS Technology
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge

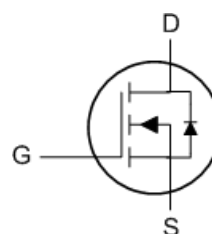
Applications

- ★ Power Tools.
- ★ UPS
- ★ Synchronous Rectification in SMPS.

Product Summary

BVDSS	RDS(on)	ID
80V	6.5mΩ	120A

TO220 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	±20	V
$I_{D@T_C=25^{\circ}C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	120	A
$I_{D@T_C=100^{\circ}C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	85	A
I_{DM}	Pulsed Drain Current ²	250	A
EAS	Single Pulse Avalanche Energy ³	90.3	mJ
I_{AS}	Avalanche Current	19	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	150	W
T_{STG}	Storage Temperature Range	-55 to 175	°C
T_J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	60	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	1	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	80	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V$, $I_D=20A$	---	5	6.5	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	2	---	4	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=64V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=64V$, $V_{GS}=0V$, $T_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5V$, $I_D=20A$	---	75	---	S
R_g	Gate Resistance	$V_{DS}=0V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	0.5	---	Ω
Q_g	Total Gate Charge	$V_{DS}=40V$, $V_{GS}=10V$, $I_D=20A$	---	52.1	---	nC
Q_{gs}	Gate-Source Charge		---	12.8	---	
Q_{gd}	Gate-Drain Charge		---	14.6	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=40V$, $V_{GS}=10V$, $R_G=3\Omega$, $I_D=20A$	---	18	---	ns
T_r	Rise Time		---	9	---	
$T_{d(off)}$	Turn-Off Delay Time		---	38	---	
T_f	Fall Time		---	8	---	
C_{iss}	Input Capacitance	$V_{DS}=40V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	3109	---	pF
C_{oss}	Output Capacitance		---	811	---	
C_{rss}	Reverse Transfer Capacitance		---	19	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,5,6}	$V_G=V_D=0V$, Force Current	---	---	100	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V$, $I_S=1A$, $T_J=25^{\circ}\text{C}$	---	0.77	1.0	V
t_{rr}	Reverse Recovery Time	$I_F=20A$, $dI/dt=100A/\mu s$,	---	27	---	nS
Q_{rr}	Reverse Recovery Charge	$T_J=25^{\circ}\text{C}$	---	89	---	nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD}=25V$, $V_{GS}=10V$, $L=0.5mH$, $I_{AS}=19A$
4. The power dissipation is limited by 175 $^{\circ}\text{C}$ junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
6. Bonding wire limitation current is 85A.

Typical Characteristics

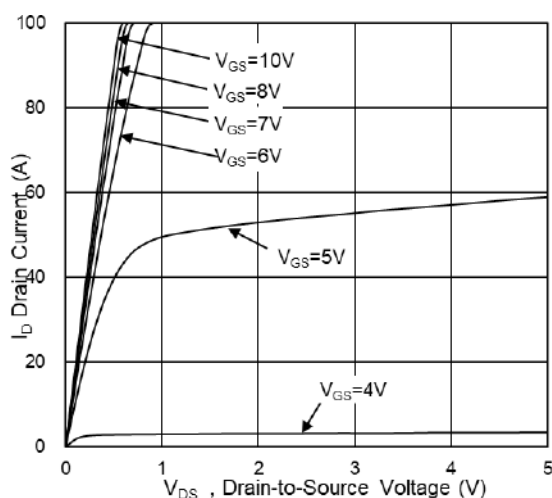


Fig.1 Typical Output Characteristics

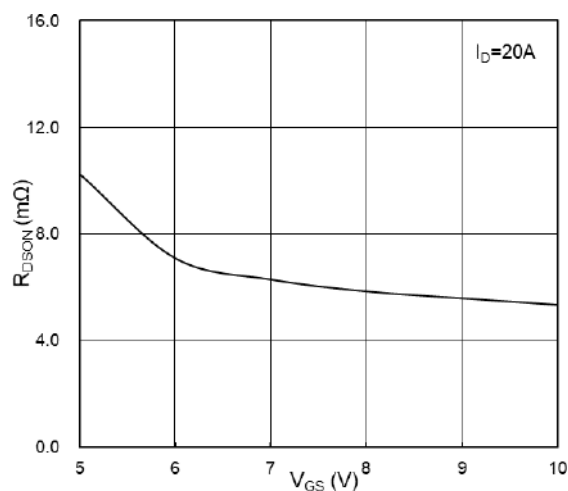


Fig.2 On-Resistance vs G-S Voltage

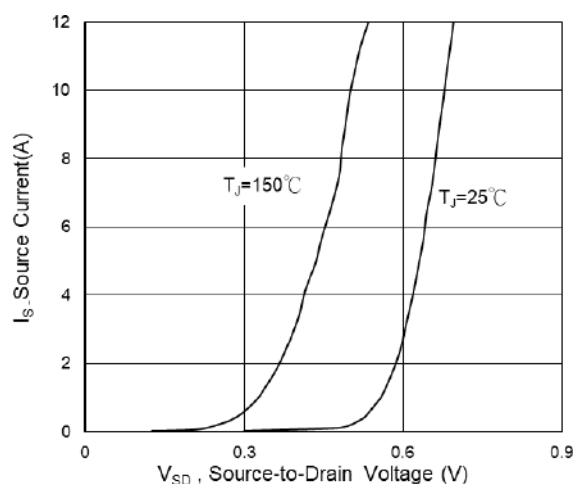


Fig.3 Source Drain Forward Characteristics

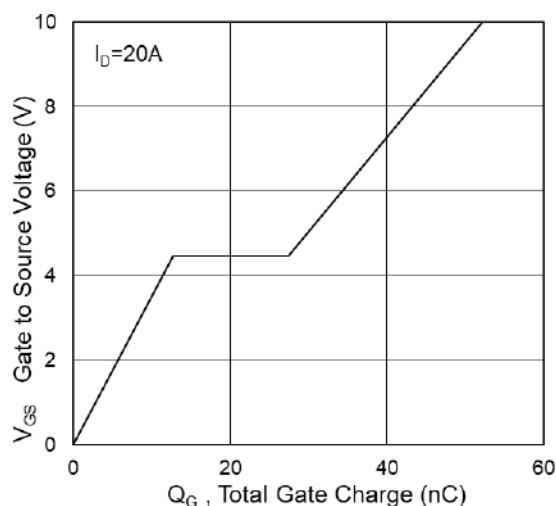


Fig.4 Gate-Charge Characteristics

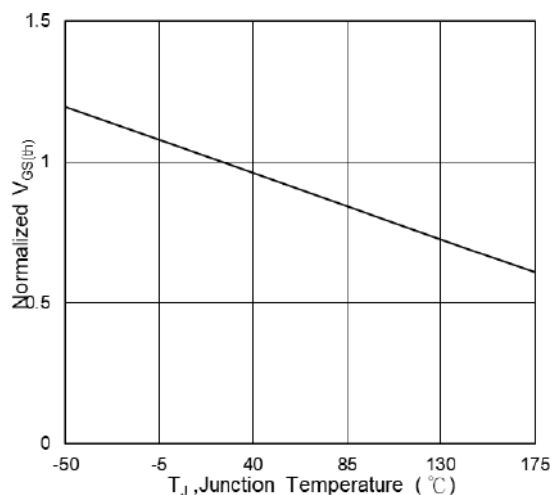


Fig.5 Normalized $V_{GS(th)}$ vs T_J

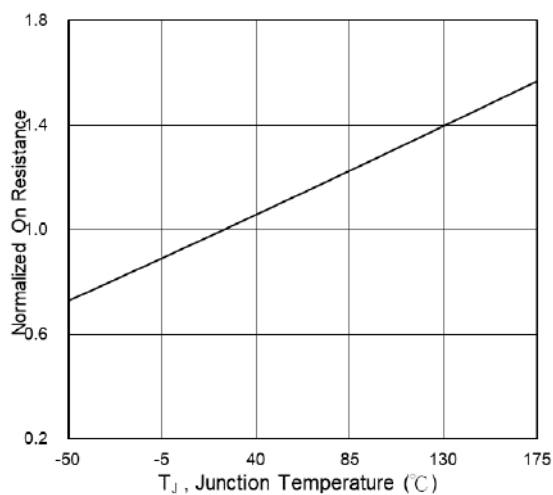


Fig.6 Normalized $R_{DS(on)}$ vs T_J

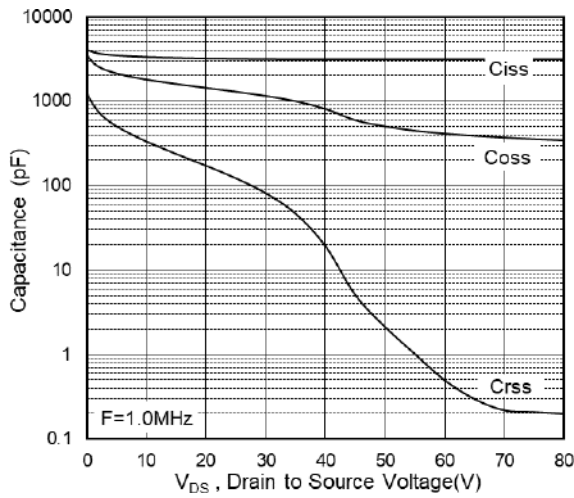


Fig.7 Capacitance

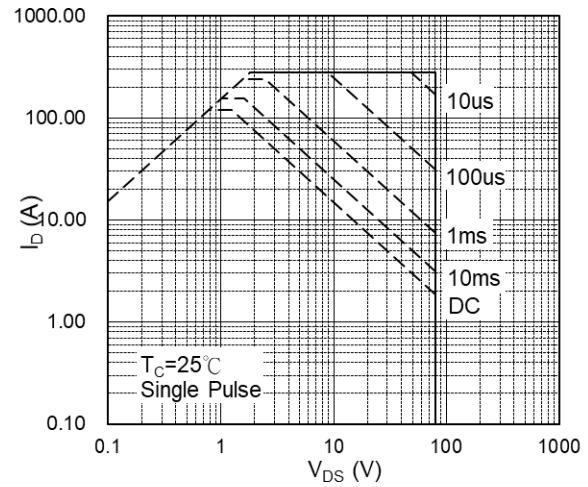


Fig.8 Safe Operating Area

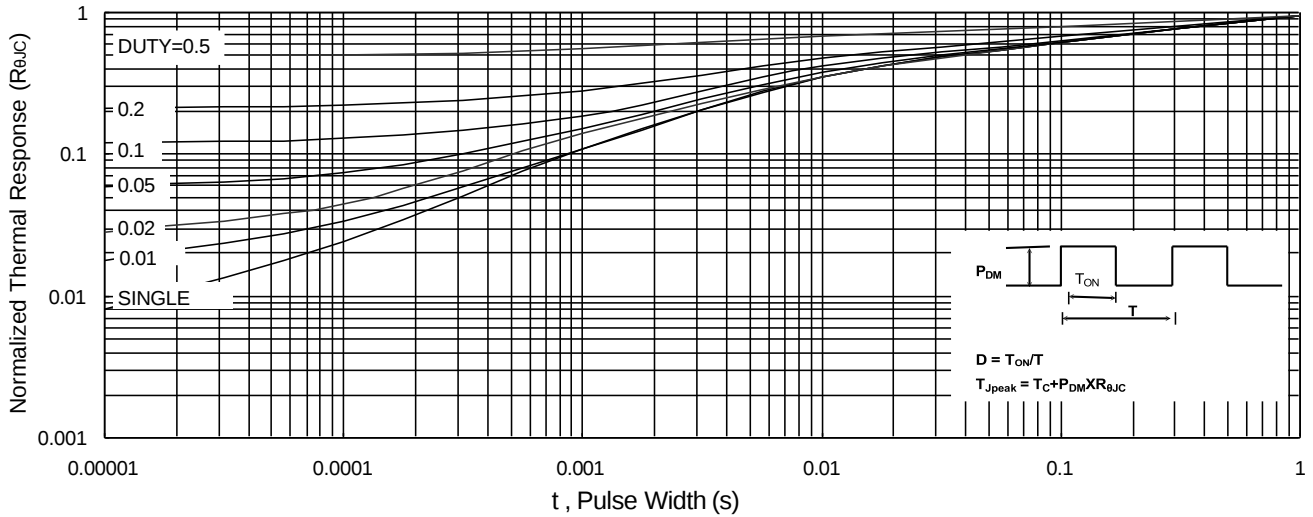


Fig.9 Normalized Maximum Transient Thermal Impedance

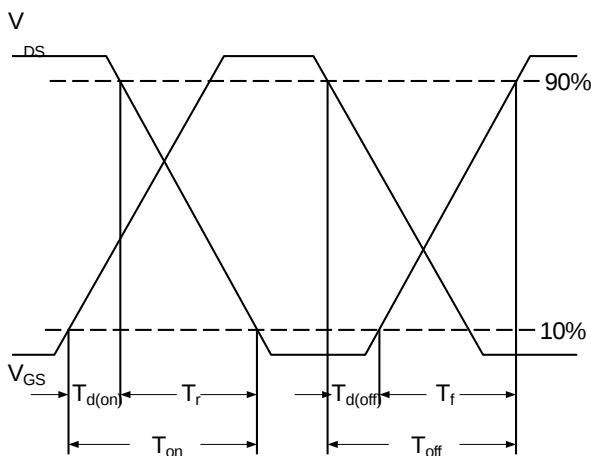


Fig.10 Switching Time Waveform

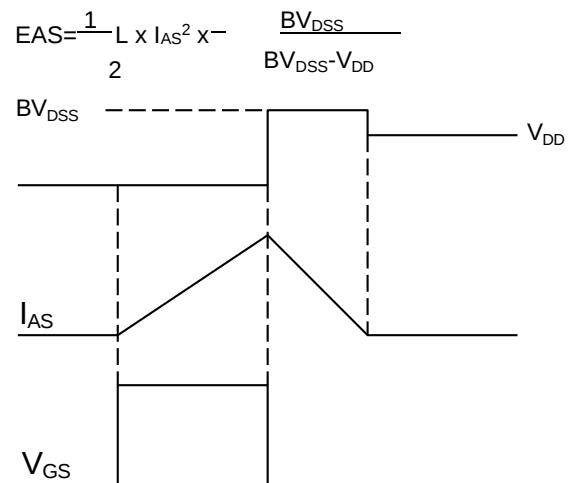


Fig.11 Unclamped Inductive Switching Waveform